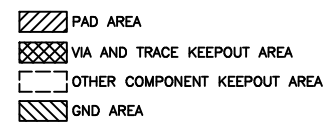
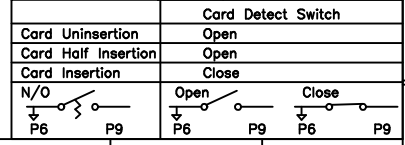


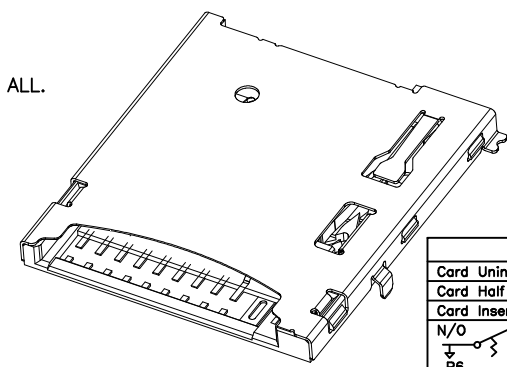
RECOMMENDED PCB LAYOUT (ALL TOLERANCE ARE ±0.05)



Pin No.	Pin Assignment
PIN1	Micro SD DAT2
PIN2	Micro SD CD/DAT3
PIN3	Micro SD CMD
PIN4	Micro SD VDD1
PIN5	Micro SD CLK
PIN6	Micro SD VSS
PIN7	Micro SD DAT0 RCLK+
PIN8	Micro SD DAT1 PCLK-
PIN9	Micro SD CD
PIN10	GND
PIN11	GND
PIN12	GND
PIN13	GND
PIN14	GND
PIN15	Micro SD VDD2
PIN16	Micro SD SWIO
PIN17	Micro SD VSS
PIN18	Micro SD D0+
PIN19	Micro SD D0-
PIN20	Micro SD VSS
PIN21	Micro SD D1-
PIN22	Micro SD D1+
PIN23	Micro SD VSS



- NOTES :
- MATERIAL :
 - 1.1 HOUSING:LCP UL94 V-0, BLACK COLOR.
 - 1.2 SHELL: Stainless Steel SUS304.
 - 1.3 CONTACT: Copper Alloy C5210.
 - FINISH :
 - 2.1 CONTACT: GOLD PLATING ON CONTACT AREA, MATTE TIN 100u"MIN ON SOLDER TAIL AREA. 50u" MIN NICKEL PLATING OVERALL.
 - 2.2 SHELL: 30U" MIN SOLDERABLE NICKEL PLATED OVER ALL.
 - Electrical Characteristics:
 - 3.1 Operating voltage : 100V AC(rms)/DC.
 - 3.2 Current rating : 0.5 A.
 - 3.3 Operating Temperature: -25°C~+85°C.
 - 3.4 Contact resistance: 100 m ohms max.
 - 3.5 Insulation resistance: 1000M ohms min. at 250VDC.
 - 3.6 Dielectric withstanding voltage:500 VAC/1minute.



PART.NO.: MR262-AP401-**

- 42: 功能区镀金1U", 锡脚镀雾纯锡至少100U"
- 43: 功能区镀金3U", 锡脚镀雾纯锡至少100U"
- 44: 功能区镀金5U", 锡脚镀雾纯锡至少100U"
- 45: 功能区镀金10U", 锡脚镀雾纯锡至少100U"
- 46: 功能区镀金15U", 锡脚镀雾纯锡至少100U"
- 47: 功能区镀金30U", 锡脚镀雾纯锡至少100U"

GENERAL TOLERANCE	DWG.NO.	MR262-AP401-00	PART.NO.	MR262-AP401-**	DRAWN	L.M.J 2021.07.12
x.±0.50	REV.	X1	TITLE	Micro SD4.0 Push H1.27 conn	CHECKED	
.x±0.25	SIZE	A4	SHEET	1/2	APPROVED	
.xx±0.15						

UNIT mm SCALE 1:1

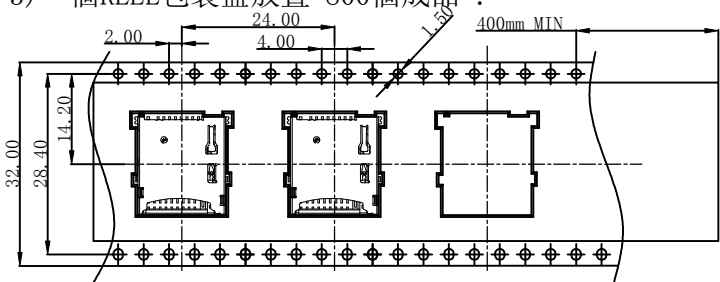
OLN 东莞市欧联电子科技有限公司
DONGGUAN OLN ELECTRONICS TECHNOLOGY CO., LTD.

东莞市欧联电子科技有限公司

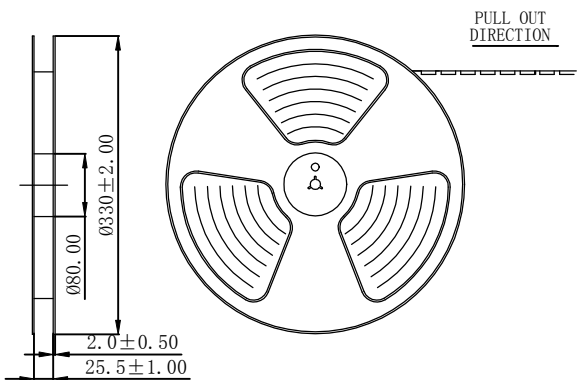
包装作业规范

包装作业图示及说明 (PACKING OPERATION DIAGRAM & INSTRUCTION)

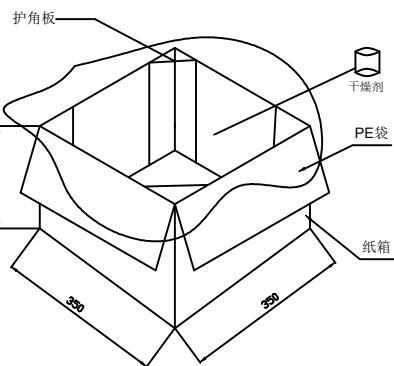
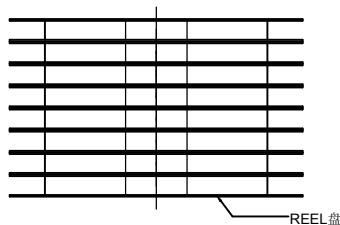
- 一.
- 1) 将成品一一放入REEL包装盘内, 依同一方向放入.
 - 2) 包装时, 如下图所示.
 - 3) 一个REEL包装盘放置 800个成品.



- 二.
- 1) 装盘前先把前面空15格, 然后再开始装盘, 尾端也需空出17格, 上带加长400mm.
 - 2) 装满成品的REEL包装盘如下图所示.



- 三.
- 1) 每箱装 8 盘REEL包装盘.
 - 2) 每箱放置 6400 PCS 的成品.



- 四.
- 1) 用TAPE将纸箱封实.



備註 (REMARK)

1. 若有未装满之零数箱, 必须以缓冲材塞满.

GENERAL TOLERANCE	DWG.NO.	MR262-AP401-00	PART.NO.	MR262-AP401-**	DRAWN	L.M.J 2021.07.12
x.±0.50	REV.	X1	TITLE	Micro SD4.0 Push H1.27 conn	CHECKED	
.x±0.25	SIZE	A4	SHEET	2/2	APPROVED	
.xx±0.15						